

IN THE SPECIFICATION

On page 4, please Amend the paragraph beginning at line 12 in accordance with the following mark-up copy:

Figures 1A-1G [[H]] are pictorial diagrams depicting a cross-sectional view of stages of preparation of an integrated circuit substrate in accordance with an embodiment of the present invention;

On page 5, please Amend the paragraph beginning at line 11 in accordance with the following mark-up copy:

Referring now to the figures and in particular to Figure 1A through 1G [[H]], a cross-sectional view of stages of preparation of a substrate in accordance with an embodiment of the present invention is shown. A first substrate stage 10A, having a dielectric layer 12 and an adhesive layer 14 disposed thereon is punched to add sprocket holes 16 forming substrate stage 10B of Figure 1B. Sprocket holes 16 are added for machine feeding the substrate stages, which are generally formed on a continuous tape, through processing machines for performing the method that prepares the substrate of the present embodiment. Substrate stage 10A may be fabricated from a dielectric film tape such as a polyimide film. Alternatively, substrate stage 10A may be

fabricated from a rigid or semi-rigid dielectric material such as polyimide resin having, in accordance with another embodiment of the present invention. Suitable tape materials are KAPTON, APICAL, UPILEX and various liquid crystal polymers (LCPs) may also be used to form the core of the substrate of the present invention. Rigid substrate layers may be cured epoxy resin, FR4, or other substrate materials commonly used to form integrated circuit substrates.